

SOT1056-1

plastic thermal enhanced very thin quad flat package; no leads; 38 terminals; resin based; body 4 x 4 x 0.9 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN38R
Package type industry code	HVQFN38R
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	30-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	[tbd]	-	0.9	0.9	mm
A ₂	package height	[tbd]	-	0.9	[tbd]	mm
n ₂	actual quantity of termination	-	-	38	-	



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2. Package outline

HVQFN38R: plastic thermal enhanced very thin quad flat package; no leads; 38 terminals; resin based; body 4 x 4 x 0.9 mm

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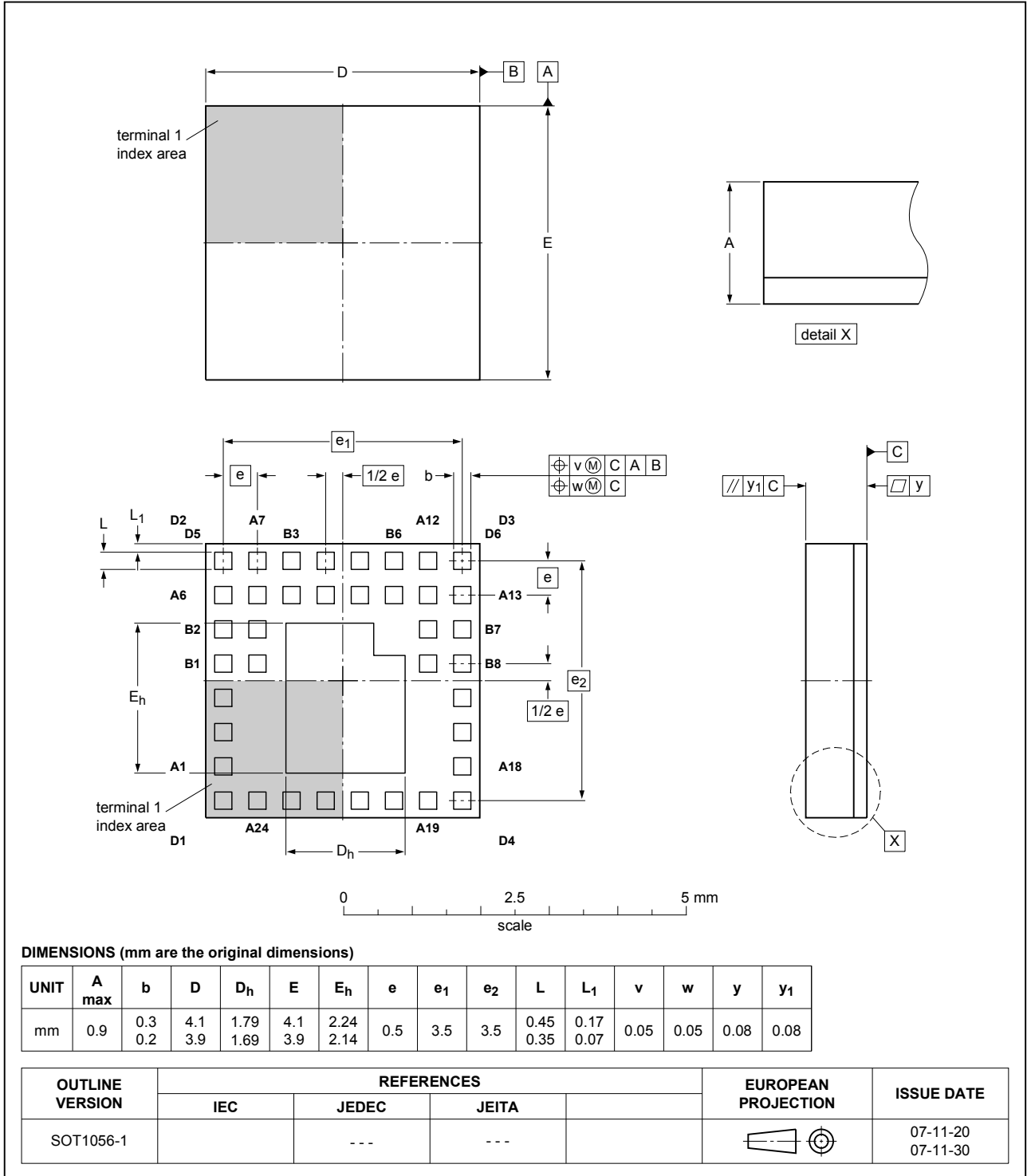


Fig. 1. Package outline HVQFN38R (SOT1056-1)

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3. Legal information

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